



## MICRON\_eMMC v5.1 153b and 100b (Automotive) Assembly Site Transition from MMY, Malaysia to MSB, Singapore

PCN: 34883

Published: 2022-12-12

**Type:** Manufacturing Site - Change or Addition

**Description:** To align with Automotive strategy, Micron is initiating an assembly site transition from MMY, Malaysia to MSB - Singapore for the below listed products. MSB is Micron's Center of Excellence for automotive assembly quality.

Samples from MSB are expected to be available the end of July 2023. Please work with your Micron representative on transition plans which are expected to begin with samples July 28, 2023. Please ensure all orders for product from MMY are placed by December 29, 2023 as shipments from MMY will end by June 28, 2024.

**Current:**

**MMY** - Micron Semiconductor Malaysia - No K93 (PLO74) Jalan Perindustrian 7 Kawasan Perindustrian Taniung Agas, Muar, JO, Malaysia 84007

**Future:**

**MMY** - Micron Semiconductor Malaysia - No K93 (PLO74) Jalan Perindustrian 7 Kawasan Perindustrian Taniung Agas, Muar, JO, Malaysia 84007

**MSB** - Micron Semi Asia Operations - 990 Bendemeer Road, Singapore 339942, Singapore

**Reason:** Manufacturing Efficiency

**Product Affected:** J35A(8GB): 100b and 153b, AIT and AAT parts J56X(32GB) both 100b and 153b, AIT and AAT parts

Affected Micron Part Number COMPONENT	Recommended Replacement	Customer Part Number
<b>MTFC16GAPALBH-AAT</b>		<b>MTFC16GAPALBH-AAT-ND</b>
<b>MTFC16GAPALBH-AIT</b>		<b>MTFC16GAPALBH-AIT-ND</b>
<b>MTFC16GAPALGT-AAT</b>		<b>557-MTFC16GAPALGT-AAT-ND</b>
MTFC16GAPALNA-AAT		
<b>MTFC16GAPALNA-AIT</b>		<b>MTFC16GAPALNA-AIT-ND</b>
<b>MTFC64GAPALNA-AIT</b>		<b>MTFC64GAPALNA-AIT-ND</b>
MTFC8GAMALBH-AAT		
<b>MTFC8GAMALBH-AIT</b>		
MTFC8GAMALHT-AAT		
MTFC8GAMALNA-AAT		
MTFC8GAMALNA-AIT		

\*Materials that have been ordered are in **bold**.

**Method of Identification:** Please refer to Micron's Customer Service Note - Product Marks, Product Labels, and Packaging Labels CSN-11 for details on Product Marks and Labels specific to the codes for countries of encapsulation.

**Micron Sites Affected:** MMY - Micron Semiconductor Malaysia  
 MSB - Micron Semi Asia Operations

Sample Available: 2023-07-28

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Qualification Reports Available: 2023-07-28

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Product Ship Date: 2023-10-26

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NOTE: Per JEDEC Standard J-STD-046 Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

**Micron Confidential and Proprietary Information**

## Attachments

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There are no attachments on this PCN